	Type	Hits	Search Text	DBs	Time Stamp	Comments
	BRS	389	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 11:14	
8	BRS	15	or\$1 or hip\$1 or die\$1 integrated adj with prevent\$3 ance\$1 with	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 11:40	
e K	BRS	27	ductor\$1 or or chip\$1 or die\$1 or (integrated adj 1)) same prevent\$3 or tenance\$1 with	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 11:41	
. 4	BRS	0	nductor\$1 or or chip\$1 or die\$1 or (integrated adj \$1)) same prevent\$3 intenance\$1 with and parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 11:41	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
Ŋ	BRS	m	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) same prevent\$3 with maintenance\$1 with manag\$6 and parameter\$1 with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 11:42	
9	BRS	7	r\$1 or die\$1 ntegrated adj ame prevent\$3 nce\$1 with arameter\$1 3 and validat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 11:43	
_	BRS	0	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) same prevent\$3 with maintenance\$1 with manag\$6 and parameter\$1 with process\$3 and (evaluat\$3 or validat\$3) and (analys\$3 or analyz\$3) and (stor\$3 or sav\$3 or record\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23	

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	10	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adjcircuit\$1)) and prevent\$3 with maintenance\$1 with manag\$6 and parameter\$1 with process\$3 and (evaluat\$3 or validat\$3) and (stor\$3 or sav\$3 or record\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23	
BRS	8	uctor\$1 or r chip\$1 or die\$1 r (integrated adj)) and prevent\$3 tenance\$1 with nd parameter\$1 ess\$3 and 3 or validat\$3) ys\$3 or analyz\$3) \$3 or sav\$3 or with (status or r condition\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
10	BRS	O	(semiconductor\$1 or wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1)) and prevent\$3 with maintenance\$1 with manag\$6 and parameter\$1 with process\$3 and (evaluat\$3 or validat\$3) and (analys\$3 or analyz\$3) and (stor\$3 or sav\$3 or record\$3) with (status or state\$1 or condition\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23	
11	BRS	2	6 % 3 (% 3) Or (% 3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 11:53	

	Туре	Hits	Search Text	DBs	Time Stamp	Comments
12	BRS	Ν	(semiconductor\$1 or wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1)) with equipment\$1 and prevent\$3 with maintenance\$1 same manag\$6 and parameter\$1 with process\$3 and (evaluat\$3 or validat\$3) with tim\$3 with cost\$3 and (analys\$3 or analyz\$3) and (stor\$3 or sav\$3 or record\$3) with (status or state\$1 or condition\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23	
13	BRS	277	702/184.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM IDB	2005/05/23	
14	BRS	477	700/95.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM IDB	2005/05/23 12:16	
15	BRS	243	700/96.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/05/23 12:16	

	Туре	Hits	Search Text	DBs	Time Stamp	Comments
16	BRS	40	(semiconductor\$1 or wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1)) with equipment\$1 and prevent\$3 with maintenance\$1 and parameter\$1 with process\$3 Jand (evaluat\$3 or validat\$3) and (analys\$3 or validat\$3) and (stor\$3 or sav\$3 or record\$3) with (status or state\$1 or condition\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:18	
17	BRS	1178	702/176,177,178,184,187.cc ls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/05/23 13:06	
18	BRS	4501	700/12,14,17,19,108,121,17 4,175,176,178,180.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/05/23 12:27	
19	BRS	5382	700/12,14,17,19,108,117,12 1,174,175,176,178,180.ccls	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/05/23 12:27	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
20	BRS	2 9		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:28	
21	BRS	0	19,108,117,1 5,178,180.ccl 5,178,180.ccl 5,178,180.ccl 3 with and evaluat\$3 or evaluat\$3 or th tim\$3 with	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:29	
22	BRS	0	semiconductor\$1 with process\$3 with maintenance\$1 and (validat\$3 or evaluat\$3 or estimat\$3) with tim\$3 with cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:29	

	Туре	Hits	Search Text	DBs	Time Stamp	Comments
23	BRS		(700/12,14,17,19,108,117,1 21,174,175,176,178,180.ccl s.) and semiconductor\$1 with process\$3 and prevent\$3 with maintenance\$1 and (validat\$3 or evaluat\$3 or estimat\$3) with tim\$3 with cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:34	
24	BRS	0	17,19,108,117,1 176,178,180.ccl iiconductor\$1 s\$3 with and prevent\$3 nance\$1 and or evaluat\$3 or with tim\$3 with	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:34	
25	BRS	m	nductor\$1 same s\$3 with parameter\$1 event\$3 with nance\$1 and at\$3 or evaluat\$3 or c\$3) with tim\$3 with	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:45	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
26	BRS	0	semiconductor\$1 with equipment\$1 with product\$1 same prevent\$3 with maintenance\$1 and process\$3 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:53	
27	BRS	15	semiconductor\$1 with equipment\$1 and semiconductor\$1 with product\$1 and prevent\$3 with maintenance\$1 and process\$3 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:47	
28	BRS	2		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:48	
29	BRS	, —1		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:50	

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	7	semiconductor\$1 with equipment\$1 and semiconductor\$1 with product\$1 and prevent\$3 with maintenance\$1 and process\$3 with parameter\$1 and cost with tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:50	
BRS	9	ctor\$1 or chip\$1 or die\$1; (integrated adj) with broduct\$1; nt\$3 with se\$1 and with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23	
BRS	9	\$1 or p\$1 or die\$1 tegrated adj th th th with and parameter\$1 h tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:54	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
33	BRS	8	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with equipment\$1 with product\$1 same prevent\$3 with maintenance\$1 and process\$3 with parameter\$1 and (estimat\$3 or evaluat\$3 or validat\$3) with cost\$3 with tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:55	
34	BRS	1.	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adjcircuit\$1)) with maintenance\$1 and process\$3 with parameter\$1 and equipment\$1 with parameter\$1 and maintenance\$1 with cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
35	BRS		(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or [integrated adj circuit\$1) with manag\$6 and (evaluat\$3 or estimat\$3 or validat\$3) with maintenance\$3 with tim\$3 with maintenance\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:01	
36	BRS		(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with maintenance\$1 and (evaluat\$3 or estimat\$3 or validat\$3) with cost\$3 with tim\$3 with maintenance\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:02	

6/8/05, EAST Version: 2.0.1.4

	Туре	Hits	Search Text	DBs	Time Stamp	Comments
37	BRS	0	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or ICs or (integrated adj circuit\$1)) with maintenance\$1 and (evaluat\$3 or estimat\$3 or validat\$3 with cost\$3 with maintenance\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:02	·
38	BRS	1779	705/7,11.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:04	
39	BRS	3388		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/05/23 13:07	
40	BRS	34		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM IDB	2005/05/23 13:08	
41	BRS	7	,177,178,182,18 87.ccls.) and or\$1 with \$1 with manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/05/23	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
42	BRS	0	182,18 and anag\$6 \$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23	
43	BRS	0	ag\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23	
44	BRS	0	5"/\$.ccls.) and conductor\$1 with tenance\$1 with manag\$6 (evaluat\$3 or dat\$3 or estimat\$3) cost\$3 with tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23	
45	BRS	1	("705"/\$.ccls.) and semiconductor\$1 with maintenance\$1 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:09	

6/8/05, EAST Version: 2.0.1.4

	Type	Hits	Search Text	DBs	Time Stamp	Comments
46	BRS	0	and with nd alidat\$3 or cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:09	
47	BRS	1	("705"/\$.ccls.) and semiconductor\$1 with maintenance\$1 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:23	
48	BRS	2	semiconductor\$1 with maintenance\$1 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 same tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:12	
49	BRS		semiconductor\$1 same prevent\$3 with maintenance\$1 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 same tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:16	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
50	BRS	10	0 t o t o 1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:17	
51	BRS	11	(wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1) or semiconductor\$1) same prevent\$3 with maintenance\$1 and (evaluat\$3 or validat\$3 or estimat\$3 pr predict\$3) with cost\$3 same tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:17	
52	BRS	8 9	r\$1 o es or grate micon nt\$3 enanc uat\$3 cost\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23	-

	Type	Hits	Search Text	DBs	Time Stamp	Comments
23	BRS		(wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1) or semiconductor\$1) and prevent\$3 with manag\$6 and (evaluat\$3 or validat\$3 or estimat\$3 pr predict\$3) with cost\$3 same tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:17	
54	BRS	, , ,	"6327521".PN.	USPAT; USOCR	2005/05/23 13:19	
55	BRS	H	"6192287".PN.	USPAT; USOCR	2005/05/23 13:19	
56	BRS	П	"6090632".PN.	USPAT; USOCR	2005/05/23 13:20	
57	BRS	H	"5940300".PN.	USPAT; USOCR	2005/05/23 13:20	
58	BRS	\vdash	"5910011".PN.	USPAT; USOCR	2005/05/23 13:21	
59	BRS	H	"4720806".PN.	USPAT; USOCR	2005/05/23 13:21	
09	BRS	 1	"5327349".PN.	USPAT; USOCR	2005/05/23 13:21	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
61	BRS	4	("705"/\$.ccls.) and (wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1) or semiconductor\$1) with maintenance\$1 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23	
62	BRS	0	("705"/\$.ccls.) and (wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1) [or semiconductor\$1) with maintenance\$1 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with tim\$3 with prevent\$3 with maintenance\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
63	BRS	O	("705"/\$.ccls.) and (wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1) or semiconductor\$1) with equipment\$1 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with tim\$3 with prevent\$3 with	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:25	·
64	BRS		(wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1) or semiconductor\$1) with (workpiece\$1 or equipment\$1) and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with maintenance\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:26	

 Type	Hits	Search Text	DBs	Time Stamp	Comments
 BRS	0	(wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1) or semiconductor\$1) and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with tim\$3 with prevent\$3 with maintenance\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:26	
 BRS	1	or I ted ondu \$3 % on ten onten onten	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:26	
 BRS	1	(piece\$1 or workpiece\$1) with (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with equipment\$1 same prevent with maintenance\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:33	•
 IS&R	2	("4860571").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/05/23 13:33	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
69	BRS	0	"6782302".uref.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/05/23	
70	BRS	0	prevent\$3 with maintenance\$1 with (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workiece\$1) with equipment\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:57	
71	BRS	0	prevent\$3 with maintenance\$1 same (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workiece\$1) with	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:57	

	Туре	Hits	Search Text	DBs	Time Stamp	Comments
72	BRS	17	prevent\$3 with maintenance\$1 and (semicopnductor\$1 or K or K or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workiece\$1) with	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:59	
73	BRS	8	with s\$1 and sctor\$1 or IC or ICs or d adj circuit\$1) dies or chip\$1) s\$1 or with l and cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:00	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
74	BRS	0	prevent\$3 with maintenance\$1 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workiece\$1 with equipment\$1 with	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:01	
75	BRS		prevent\$3 with maintenance\$1 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with product\$1 with (piece\$1 or workiece\$1) same equipment\$1 with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:01	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
92	BRS	55		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:02	
7.7	BRS	1	h or ICs or ircuit\$1) chip\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:02	
78	BRS	. 7	or ICs or ircuit\$1) chip\$1) prevent\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:07	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
	BRS	0	(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) with (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workpiece\$1) with equipment\$1 with prevent\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:06	
Ш	BRS	0	(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) same (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workpiece\$1) with equipment\$1 with prevent\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23	

Туре	Hits	Search Text	DBs	Time Stamp	Comments
BRS	0	(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) same (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workpiece\$1) with equipment\$1 same prevent\$3 with maintenance\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:06	·
BRS	4	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with prevent\$3 with manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:09	
BRS	7	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or dies or chip\$1) with prevent\$3 with maintenance\$1 same manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:09	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
84	BRS	55	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or dies or chip\$1) with prevent\$3 with maintenance\$1 and manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:09	
82	BRS	4 9	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or dies or chip\$1) with prevent\$3 with maintenance\$1 with cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:10	
98	BRS	0	semicopnductor\$1 with prevent\$3 with maintenance\$1 with cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/05/23 14:10	
87	BRS	5 8	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:21	

Type		Hits	Search Text	DBs	Time Stamp	Comments
BRS	7		(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 and (evaluat\$3 or validat\$3 or estimat\$3 or predict\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:18	
BRS	1740	40	451/1,8.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/05/23 14:18	
BRS			(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with process\$3 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with equipment\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23	

	Type	Hits	Search Text	DBs	Time Stamp Comments	Comments	
91	BRS		(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 with manag\$6 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with process\$3 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with process\$3 circuit\$1) with process\$3 circuit\$1) with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23	·	
			equipment\$1				

Type	e Hits	Search Text	DBs	Time Stamp Comments	Comments
92 BRS		(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with manag\$6 and (semicopnductor\$1 or ICs or (integrated adj circuit\$1)) with process\$3 and (semicopnductor\$1 or Wafer\$1 or IC or ICs or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with process\$3 and (semicopnductor\$1 or IC or ICs or (integrated adj circuit\$1)) with equipment\$1 and process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
e 6	BRS	9	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 and (semicopnductor\$1 or Vintegrated adj circuit\$1)) with process\$3 and (semicopnductor\$1 or wafer\$1 or IC or ICs or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with equipment\$1 and process\$3 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23	/
94	BRS	343	438/5.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/05/23	

Comments		
Time Stamp	2005/05/23	2005/05/23
DBs	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
Search Text	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with process\$3 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with equipment\$1 and process\$3 with parameter\$1 and user\$1 with interface\$1	ppnductor\$1 or or IC or ICs or ated adj (\$1)) with prevent\$3 (intenance\$1 with and user\$1 with
Hits	0	0
Type	BRS	BRS
	დ დ	96

	Туре	Hits	Search Text	DBs	Time Stamp	Comments
97	BRS	0	(semicopnductor\$1 or wafer\$1 or IC or ICs or U; (integrated adj circuit\$1)) with prevent\$3 J with maintenance\$1 with II cost\$3 with interface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:32	
86	BRS	0	t \$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:32	
<u>ი</u>	BRS	· 0	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 and user\$1 with interface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:33	
100	BRS		(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 and interface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 15:22	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
101	BRS	0	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 USPAT; ISPAT; with maintenance\$1 with cost\$3 and computer\$1 with interface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23	
102	BRS	-Τ	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated ad; circuit\$1)) with prevent\$3 USPAT; EPO; with maintenance\$1 with cost\$3 and interface\$1 with (record\$3 or sav\$3 or stor\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:39	
601	BRS	0	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 and interface\$1 with database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:39	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
104	BRS	0	or validat\$3 or or predict\$3) 3 with prevent\$3 enance\$1 with h uctor\$1 or IC or ICs or d adj	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 15:23	
105	BRS	0	or validat\$3 or or predict\$3) nt\$3 with e\$1 with cost\$3 copnductor\$1 or IC or ICs or d adj	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 15:24	·
106	BRS		(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) with prevent\$3 with maintenance\$1 with cost\$3 and (semicopnductor\$1 or wafer\$1 or IC or ICs or integrated adj circuit\$1)) with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
107	BRS	0	or validat\$3 or or predict\$3) nt\$3 with e\$1 with cost\$3 opnductor\$1 or IC or ICs or d adj) with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 15:25	
108	BRS	46	(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) same prevent\$3 with maintenance\$1 and (semicopnductor\$1 or Wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 15:25	
109	BRS	0	(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) same prevent\$3 with maintenance\$1 same cost\$3 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 15:25	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
110	BRS	0	(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) with cost\$3 same prevent\$3 with maintenance\$1 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 15:26	
111	BRS	2	or validat\$3 or r predict\$3) \$3 same ith \$1 and ctor\$1 or IC or ICs or ad; with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 15:26	
112	BRS	48	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with warn\$3 with manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 11:14	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
113	BRS	П	chip\$1 or die\$1 (integrated adj with warn\$3 % and (stor\$3 : record\$3) with	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB'	2005/06/01 11:17	
114	BRS	2	(semiconductor\$1 or die\$1 or chip\$1 or die\$1 or lC\$1 or (integrated adj US-PGPUB; circuit\$1) with (diagnos\$3 or warn\$3) with JPO; DERWENT; manag\$6 and (stor\$3 or lBM_TDB sav\$3 or record\$3) with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 11:18	
115	BRS	7	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or (integrated adj US-PGPUB; circuit\$1)) same (diagnos\$3 or warn\$3) with JPO; DERWENT; manag\$6 and (stor\$3 or record\$3) with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 11:19	

	Туре	Hits	Search Text	DBs	Time Stamp	Comments
116	BRS	41	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with manag\$6 and (stor\$3 or sav\$3 or record\$3) with process\$3 with parameter\$1 and (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 with product\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 11:23	
117	BRS	19	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or [integrated adj circuit\$1) with manag\$6 and (stor\$3 or sav\$3 or record\$3) with process\$3 with parameter\$1 and (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1) with qualit\$3 with product\$1 and (warn\$3 or notice or inform\$2)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 11:44	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
118	BRS	7	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with manag\$6 and (stor\$3 or sav\$3 or record\$3) with process\$3 with parameter\$1 and (semiconductor\$1 or (integrated adj circuit\$1)) with qualit\$3 with product\$1 and (warn\$3 or notice or inform\$2) and	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01	

	Type	Hits	Search Text	DBs	Time Stamp Comments	Comments
119	BRS	0	miconductor\$1 or er\$1 or chip\$1 or die\$1 IC\$1 or (integrated adj cuit\$1)) with manag\$6 (stor\$3 or sav\$3 or ord\$3) with process\$3 h parameter\$1 and aluat\$3 or estimat\$3 or idat\$3 or predict\$3) h (semiconductor\$1 or er\$1 or chip\$1 or die\$1 IC\$1 or (integrated adj cuit\$1)) with qualit\$3 h product\$1 and (warn\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01	
			or notice or inform\$2)			

	Type	Hits	Search Text	DBs	Time Stamp Comments	Comments
120	BRS	0	ctor\$1 or chip\$1 or die\$1 (integrated adj) with manag\$6 ase or file\$1 or sav\$3 or with \$1 or status or ith process\$3 eter\$1 and	US-PGPUB; USPAT; EPO; JPO; DERWENT;	2005/06/01	
			(evaluat\$3 or estimat\$3 or validat\$3 or predict\$3) with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or [integrated adjor circuit\$1) with qualit\$3 with product\$1 and (warn\$3 or notice or inform\$2)	IBM_TDB		

	Type	Hits	Search Text	DBs	Time Stamp Comments	Comments
121	BRS	0	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with manag\$6 and (database or file\$1 or stor\$3 or sav\$3 or record\$3) with (condition\$1 or status or state\$1) with process\$3 with parameter\$1 and (evaluat\$3 or estimat\$3 or validat\$3 or predict\$3) with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 12:14	

Hits	Sear	arch Text	ĎBs	Time Stamp	Comments
(semiconductor\$1 wafer\$1 or chip\$1 or IC\$1 or (integ	ch (i)	ctor\$1 or chip\$1 or die\$1 (integrated adj			
\$1)) taba	wi se) with manag\$6 ase or file\$1 or			
	av\$ ith	or	JS-PGPUB;		
(condition\$1 or status state\$1) with process\$3	1 o th	OK	USPAT; EPO; JPO; DERWENT;	2005/06/01 12:15	
with parameter\$1	ter	and	IBM_TDB		
(evaluat\$3 or validat\$3 or p	or r p	or estimat\$3 or or predict\$3)			
emi(ondi	conductor\$1 or			
Or	chl	chipsi or diesi			
or IC\$1 or (in	(in	(integrated adj			
circuit\$1)) wi	Wj) with qualit\$3			•

	Type	Hits	Search Text	DBs	Time Stamp	Comments
123	BRS	4	ctor\$1 or chip\$1 or die\$1 (integrated adj) same manag\$6 ase or file\$1 or sav\$3 or with \$1 or status or ith process\$3 eter\$1 and or estimat\$3 or or estimat\$3 or or predict\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 12:18	
			with (semiconductors] or wafer\$1 or chip\$1 or die\$1 or [C\$1] or (integrated adj circuit\$1)) with qualit\$3			

	Type	Hits	Search Text	DBs	Time Stamp	Comments
124	BRS	4	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or [integrated adjcircuit\$1]) same manag\$6 and (database or file\$1 or stor\$3 or sav\$3 or condition\$1 or status or state\$1] with process\$3 with parameter\$1 and (evaluat\$3 or estimat\$3 or validat\$3 or predict\$3) with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adjcircuit\$1) with qualit\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01	
.25	BRS	48	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with warn\$3 with manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 12:23	

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS		(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adjcircuit\$1)) with warn\$3 with manag\$6 and (condition\$1 or status or state\$1) with process\$3 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 12:23	
BRS		(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or (integrated adjcircuit\$1)) with warn\$3 with manag\$6 and (condition\$1 or status or state\$1) same process\$3 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 12:22	
BRS	Ţ	or 1 or die\$1 grated adj warn\$3 process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 12:22	

	Туре	Hits	Search Text	DBs	Time Stamp	Comments
129	BRS	e	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adjcircuit\$1)) with warn\$3 with manag\$6 and (condition\$1 or status or state\$1) with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 12:23	
130	BRS	Ω	"700"/\$.ccls. and (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) same warn\$3 with manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 12:26	
131	BRS	534	"700"/\$.ccls. and (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adjcircuit\$1)) and warn\$3 and manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 12:26	
132	BRS	<u>.</u>	ccls. and ductor\$1 or or chip\$1 or die\$1 or (integrated adj 1)) same warn\$3 ag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 12:30	

	Туре	Hits	Search Text	DBs	Time Stamp	Comments
133	BRS	195	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or [C\$1 or (integrated adj circuit\$1)) same warn\$3 same manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 12:30	
134	BRS	48	r\$1 or ip\$1 or die\$1 ntegrated adj ith warn\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06	
135	IS&R	5		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/06/06 10:29	
136	BRS	16	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with equipments with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06	
137	BRS	7	or die\$1 rated adj notice\$1 m\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 11:02	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
38	BRS	89	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or [integrated adj circuit\$1]) with equipment\$ with parameter\$1 and (notice\$1 or warn\$3 or alarm\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 11:03	
39	BRS	24	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or (integrated adj circuit\$1)) with equipment\$ with parameter\$1 and warn\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 11:02	
40	BRS	<u>.</u>	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with equipment\$ with parameter\$1 and warn\$3 and equipments	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 11:03	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
141	BRS	10	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adjcircuit\$1)) with equipment\$ with parameter\$1 and (notice\$1 or warn\$3 or alarm\$1) and equipment\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 11:05	
142	BRS	ω	or 1 or die\$1 grated adj (notice\$1 rm\$1) and ecord\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 11:06	·
143	BRS	15	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adjcircuit\$1)) with equipments and process\$3 with parameter\$1 and (notice\$1 or warn\$3 or alarm\$1) and record\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 11:55	

	Туре	Hits	Search Text	DBs	Time Stamp	Comments
144	BRS	14	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adjcircuit\$1)) with equipments and process\$3 with parameter\$1 and (notice\$1 or warn\$3 or alarm\$1) and (database\$1 or record\$3 or stor\$4 or sav\$3) and interface\$1.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06	
145	BRS	21		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06	
146	BRS	823	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or [integrated adjcircuit\$1]) with equipment\$ and process\$3 with parameter\$1 and equipment\$2 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
147	BRS	. 99	or 1 or die\$1 grated adj compar\$4 ith arameter\$1 with	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 15:40	,
148	BRS	<u></u>		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06	
149	BRS	E	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and t-test	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 15:48	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
150	BRS	24	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and one-way	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 10:16	
151	BRS	0	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adjcircuit\$1)) with product\$1 with qualit\$3 and one-way with (analys\$3 or analyz\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 15:48	
152	BRS	8_	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adjcircuit\$1)) with product\$1 with qualit\$3 and one with way with (analys\$3 or analyz\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 15:50	
153	BRS	22	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or [integrated adj circuit\$1) with product\$1 with qualit\$3 and anova	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 16:01	

	Туре	Hits	Search Text	DBs	Time Stamp	Comments
154	BRS	4	or die\$1 cated adj product\$1 anova	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 15:56	
155	BRS	8	ά. Ω. Ω.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 16:13	
156	BRS	10	T :D H	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06	
157	BRS	114	1; 1;	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 16:23	

-	Туре	Hits	Search Text	DBs	Time Stamp	Comments
158 E	BRS	9	or l or die\$1 grated adj test\$3 th	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 16:25	
159 E	BRS	27	ctor\$1 or chip\$1 or die\$1 (integrated adj) with test\$3 t\$3 with 1 and database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 16:25	
160 E	BRS	17	tor\$1 or chip\$1 or die\$1 (integrated adj with test\$3 \$3 with and database t\$3 or r evaluat\$3 or r predict\$3) s\$3 or	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06	

	Туре	Hits	Search Text	DBs	Time Stamp	Comments
161	BRS	110		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 10:17	
162 E	BRS	-	r or die\$1 ated adj roduct\$1 tatus or pment\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 10:21	
163 E	BRS	7	or 1 or die\$1 grated adj product\$1 d	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 10:18	

	Туре	Hits	Search Text	DBs	Time Stamp	Comments
164	BRS	9	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or [integrated adj circuit\$1) with product\$1 with qualit\$3 and (condiction\$1 or status or state\$1) with equipment\$1 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 10:22	
165	BRS	9	or 1 or die\$1 grated adj product\$1 d status or uipment\$1 and arameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 10:50	
166	IS&R	7	("6449524").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/06/07 10:28	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
167	BRS	65		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 10:41	
168	BRS	. 9	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (condiction\$1 or status or state\$1) with equipment\$1 and (estimat\$3 or validat\$3 or evaluat\$3 or predict\$3) with qualit\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 10:30	·
169	BRS	9		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 10:41	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
170	BRS	0	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (condiction\$1 or status or state\$1) with equipment\$1 with parameter\$1 and equipment\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 10:50	·
171	BRS	ω		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07	
172	BRS	65	7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 10:54	

	Type	Hits	Search Text	DBs	Time Stamp Comments	Comments
73	BRS	18	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or lC\$1 or (integrated adj circuit\$1) with product\$1 with qualit\$3 and (condiction\$1 or status or state\$1) with equipment\$1 and database\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 10:55	
74	BRS	4	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or lC\$1 or (integrated adj circuit\$1) with product\$1 with qualit\$3 and (condiction\$1 or status or state\$1) with equipment\$1 and database\$1 and (record\$3 or stor\$3 or sav\$3) with measur\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07	

	Туре	Hits	Search Text	DBs	Time Stamp	Comments
175	BRS	17	or l or die\$1 grated adj product\$1 d status or uipment\$1 nd r\$3 or ict\$3 or ict\$3 or luat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 11:07	
176	BRS	4	chor\$1 or die\$1 (integrated adj) with product\$1 t\$3 and n\$1 or status or ith equipment\$1 se\$1 and or stor\$3 or credict\$3 or or estimat\$3 or or estimat\$3 or ents	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 11:08	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
177	BRS	<u>ი</u>	chip\$1 or die\$1 (integrated adj with qualit\$3 tion\$1 or tate\$1 with and database\$1 \$3 or stor\$3 or restimat\$3 or revaluat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07	
178	BRS	o	chip\$1 or die\$1 (integrated adj with qualit\$3 tion\$1 or tate\$1 or and database\$1 \$3 or stor\$3 or restimat\$3 or revaluat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
179	BRS	76	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or (integrated adj circuit\$1)) with qualit\$3 and (record\$3 or stor\$3 or sav\$3 or database) with equipment with (parameter\$1 or measur\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 11:12	
180	BRS	5.1	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adjcircuit\$1)) with qualit\$3 and (record\$3 or stor\$3 or sav\$3 or database) with (parameter\$1 or measur\$6) and (record\$3 or stor\$3 or sav\$3 or database) with process\$3 with (parameter\$1 or measur\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 11:13	

Type	Hits	Search Text	DBs	Time Stamp Comments	Comments
181 BRS 24		(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or lC\$1 or (integrated adjcircuit\$1)) with qualit\$3 and (record\$3 or stor\$3 or sav\$3 or database) with (parameter\$1 or measur\$6) and (record\$3 or stor\$3 or sav\$3 or database) with process\$3 with (parameter\$1 or measur\$6) and (compar\$4 or differen\$2) with	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 11:14	·

	Туре	Hits	Search Text	DBs	Time Stamp Comments	Comments
182	BRS	15	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or (integrated adjor circuit\$1)) with qualit\$3 and (record\$3 or stor\$3 or sav\$3 or database) with (parameter\$1 or measur\$6) and (record\$3 or stor\$3 or sav\$3 or database) with process\$3 with (parameter\$1 or measur\$6) and (compar\$4 or differen\$2) with compar\$4 or	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07	

	Туре	Hits	Search Text	DBs	Time Stamp	Comments
183	BRS	2	(record\$3 or stor\$3 or sav\$3 or database) with equipment with (status\$2 or condition\$1 or state\$1) and (inspect\$3 or validat\$3 or estimat\$3 or validat\$3) with test\$3 with (semiconductor\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adjcircuit\$1)) with product\$1 and statistic\$4 with (analyz\$3 or analys\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 11:26	
184	BRS	4	0 c c c c c c c c c c c c c c c c c c c	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07	

	Туре	Hits	Search Text	DBs	Time Stamp	Comments
185	BRS	7	(record\$3 or stor\$3 or sav\$3 or database) with equipment\$1 with (status\$2 or condition\$1 or state\$1) and (inspect\$3 or estimat\$3 or validat\$3) with test\$3 with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adjcircuit\$1) with product\$1 and (analyz\$3 or analys\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07	
186	BRS	. 4	or stor\$3 or atabase) with 1 with (status\$2 on\$1 or state\$1) ct\$3 or or estimat\$3 or or predict\$3) 3 with ctor\$1 or chip\$1 or die\$1 (integrated adj 2\$3 or analys\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07	

	Туре	Hits	Search Text	DBs	Time Stamp	Comments
	BRS	24	\$2 1) 1) 4) 3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 11:54	
88	BRS	14	r stor\$3 or tabase) with with (status\$2 n\$1 or state\$1) t\$3 or r estimat\$3 or r predict\$3) onductor\$1 or chip\$1 or die\$1 (integrated adj with product\$1 \$3 or analys\$3) ic\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07	

	Туре	Hits	Search Text	DBs	Time Stamp	Comments
189	BRS	3115	365/201.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/06/07	
190	BRS	0	365/e21.525.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/06/07	
191	BRS	1252	257/e21.525.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/06/07	
192	BRS	47	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 and (analyz\$3 or analys\$3) with equipment\$1 with parameter\$1	JS-PGPUB; JSPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 13:20	
193	BRS	31	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or [integrated adjcircuit\$1) with qualit\$3 and (analyz\$3 or analys\$3) with equipment\$1 with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 13:20	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
94	BRS	Ŋ	tor\$1 or chip\$1 or die\$1 (integrated adj with qualit\$3 t\$1 and r analys\$3) ent\$1 with	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 13:22	
95	BRS	2		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 13:23	
96	BRS	4	tor\$1 or chip\$1 or die\$1 (integrated adj with qualit\$3 t\$1 with with	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 13:23	

	Туре	Hits	Search Text	DBs	Time Stamp	Comments
197	BRS	ω	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adjcircuit\$1)) with qualit\$3 with product\$1 same equipment\$1 with	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 13:23	
198	BRS	8	or\$1 or chip\$1 or die\$1 integrated adj with qualit\$3 \$1 and t-	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 16:07	
199	BRS	29	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with t-test\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/06/07 16:06	
200	BRS	155	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or lC\$1 or (integrated adj circuit\$1)) and qualit\$3 with product\$1 and t-test\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 16:07	